

## General Description

FSMOS<sup>®</sup> MOSFET is based on Oriental Semiconductor's unique device design to achieve low  $R_{DS(ON)}$ , low gate charge, fast switching and excellent avalanche characteristics. The low  $V_{th}$  series is specially designed to use in synchronous rectification power systems with low driving voltage.

## Features

- Low  $R_{DS(ON)}$  & FOM
- Extremely low switching loss
- Excellent reliability and uniformity
- Fast switching and soft recovery



## Applications

- PD charger
- Motor driver
- Switching voltage regulator
- DC-DC convertor
- Switched mode power supply

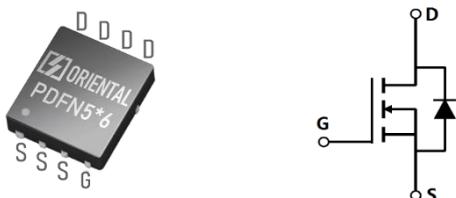
## Key Performance Parameters

Parameter	Value	Unit
$V_{DS, min} @ T_{j(max)}$	40	V
$I_D, pulse$	600	A
$R_{DS(ON) max} @ V_{GS}=10V$	1.5	mΩ
$Q_g$	96.8	nC

## Marking Information

Product Name	Package	Marking
SFS04R02GF	PDFN5*6	SFS04R02G

## Package & Pin information



**Absolute Maximum Ratings** at  $T_j=25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	$V_{DS}$	40	V
Gate source voltage	$V_{GS}$	$\pm 20$	V
Continuous drain current <sup>1)</sup> , $T_C=25^\circ\text{C}$	$I_D$	200	A
Pulsed drain current <sup>2)</sup> , $T_C=25^\circ\text{C}$	$I_{D,\text{pulse}}$	600	A
Continuous diode forward current <sup>1)</sup> , $T_C=25^\circ\text{C}$	$I_S$	200	A
Diode pulsed current <sup>2)</sup> , $T_C=25^\circ\text{C}$	$I_{S,\text{Pulse}}$	600	A
Power dissipation <sup>3)</sup> , $T_C=25^\circ\text{C}$	$P_D$	132	W
Single pulsed avalanche energy <sup>5)</sup>	$E_{AS}$	200	mJ
Operation and storage temperature	$T_{stg}, T_j$	-55 to 150	$^\circ\text{C}$

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	0.95	$^\circ\text{C/W}$
Thermal resistance, junction-ambient <sup>4)</sup>	$R_{\theta JA}$	62	$^\circ\text{C/W}$

**Electrical Characteristics** at  $T_j=25^\circ\text{C}$  unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	$BV_{DSS}$	40			V	$V_{GS}=0 \text{ V}, I_D=250 \mu\text{A}$
Gate threshold voltage	$V_{GS(\text{th})}$	1.0		2.5	V	$V_{DS}=V_{GS}, I_D=250 \mu\text{A}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		1.25	1.50	$\text{m}\Omega$	$V_{GS}=10 \text{ V}, I_D=55 \text{ A}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		2.0	3.0	$\text{m}\Omega$	$V_{GS}=6 \text{ V}, I_D=55 \text{ A}$
Gate-source leakage current	$I_{GSS}$			100	$\text{nA}$	$V_{GS}=20 \text{ V}$
				-100		$V_{GS}=-20 \text{ V}$
Drain-source leakage current	$I_{DSS}$			1	$\mu\text{A}$	$V_{DS}=40 \text{ V}, V_{GS}=0 \text{ V}$

### Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C <sub>iss</sub>		6587		pF	V <sub>GS</sub> =0 V, V <sub>DS</sub> =20 V, f=100 kHz
Output capacitance	C <sub>oss</sub>		2537		pF	
Reverse transfer capacitance	C <sub>rss</sub>		178		pF	
Turn-on delay time	t <sub>d(on)</sub>		26.6		ns	V <sub>GS</sub> =10 V, V <sub>DS</sub> =20 V, R <sub>G</sub> =2 Ω, I <sub>D</sub> =20 A
Rise time	t <sub>r</sub>		9.3		ns	
Turn-off delay time	t <sub>d(off)</sub>		96		ns	
Fall time	t <sub>f</sub>		39.3		ns	

### Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q <sub>g</sub>		96.8		nC	V <sub>GS</sub> =10 V, V <sub>DS</sub> =20 V, I <sub>D</sub> =20 A
Gate-source charge	Q <sub>gs</sub>		14.5		nC	
Gate-drain charge	Q <sub>gd</sub>		18.4		nC	
Gate plateau voltage	V <sub>plateau</sub>		2.7		V	

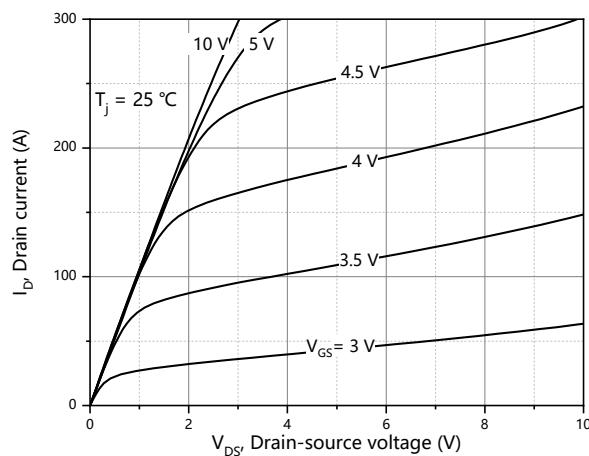
### Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V <sub>SD</sub>			1.3	V	I <sub>S</sub> =20 A, V <sub>GS</sub> =0 V
Reverse recovery time	t <sub>rr</sub>		66.2		ns	V <sub>R</sub> =20 V, I <sub>S</sub> =20 A, di/dt=100 A/μs
Reverse recovery charge	Q <sub>rr</sub>		66.1		nC	
Peak reverse recovery current	I <sub>rrm</sub>		2		A	

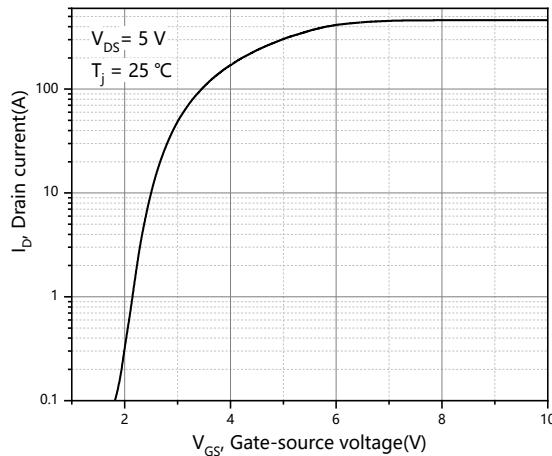
### Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R<sub>θJA</sub> is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>a</sub>=25 °C.
- 5) V<sub>DD</sub>=30 V, V<sub>GS</sub>=10 V, L=0.3 mH, starting T<sub>j</sub>=25 °C.

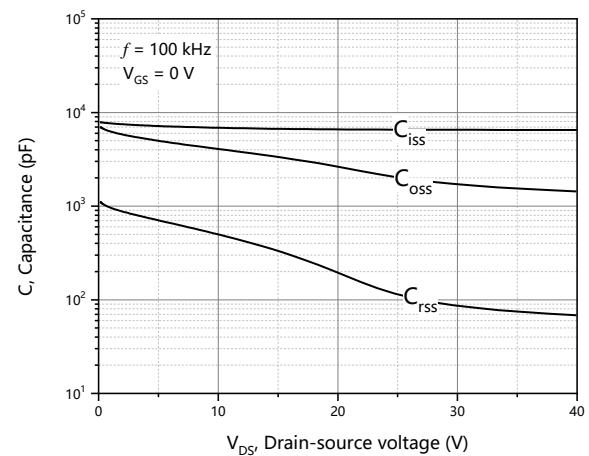
## Electrical Characteristics Diagrams



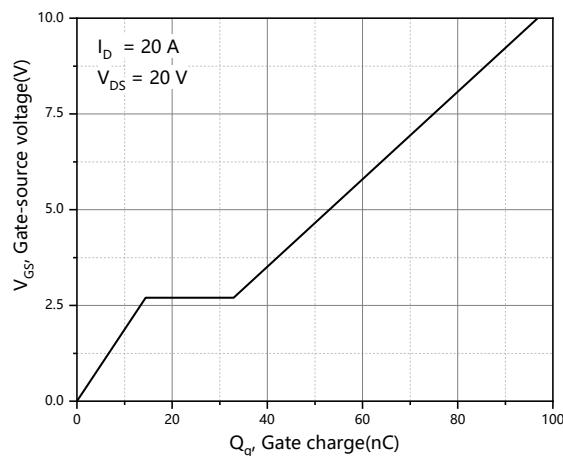
**Figure 1. Typ. output characteristics**



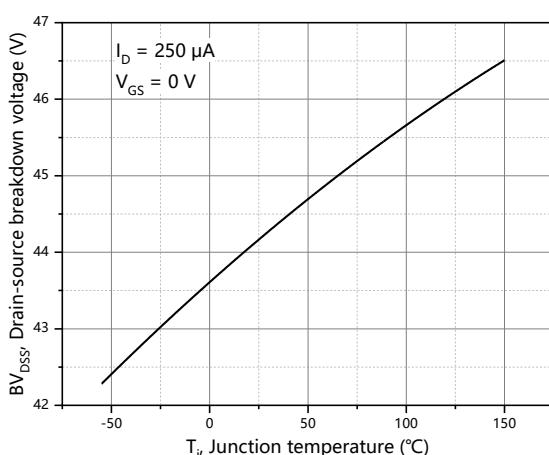
**Figure 2. Typ. transfer characteristics**



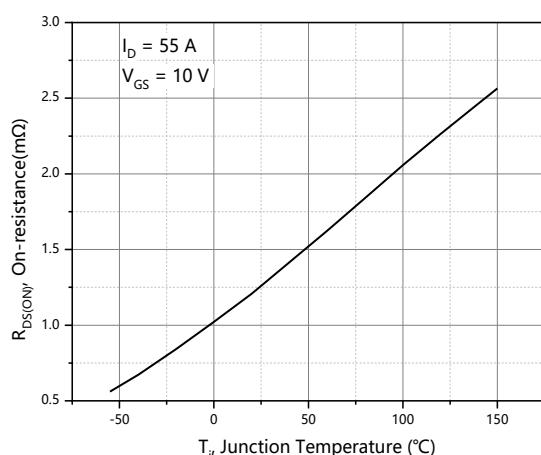
**Figure 3. Typ. capacitances**



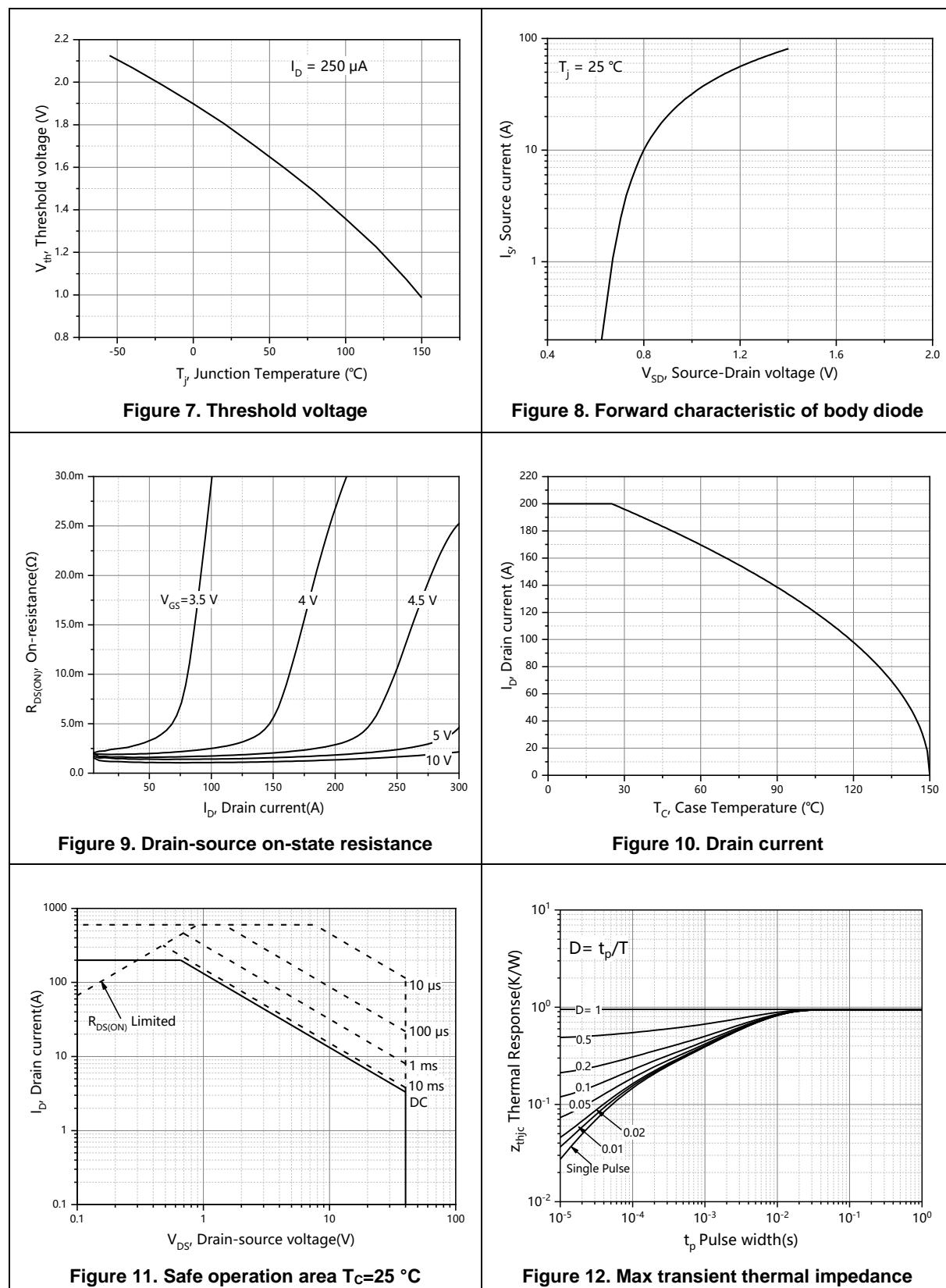
**Figure 4. Typ. gate charge**



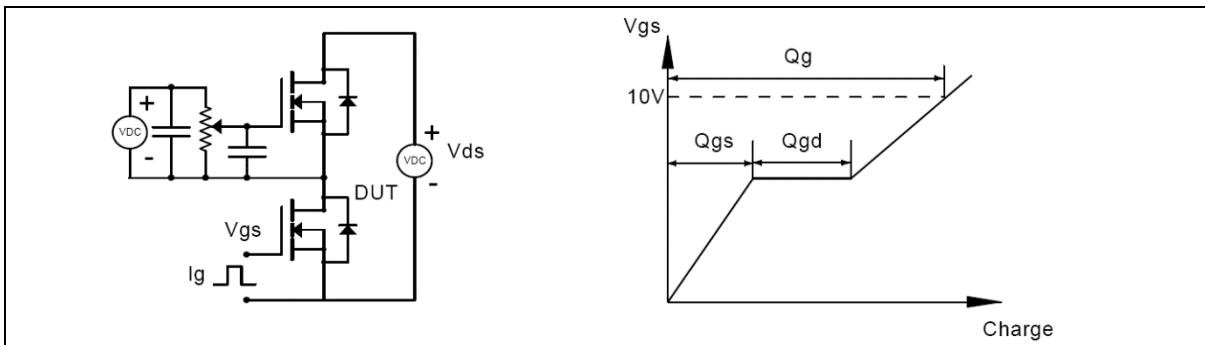
**Figure 5. Drain-source breakdown voltage**



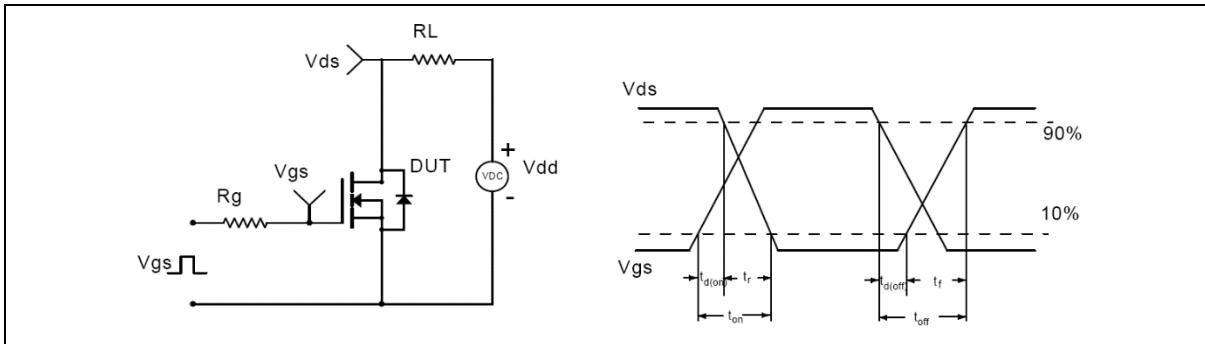
**Figure 6. Drain-source on-state resistance**



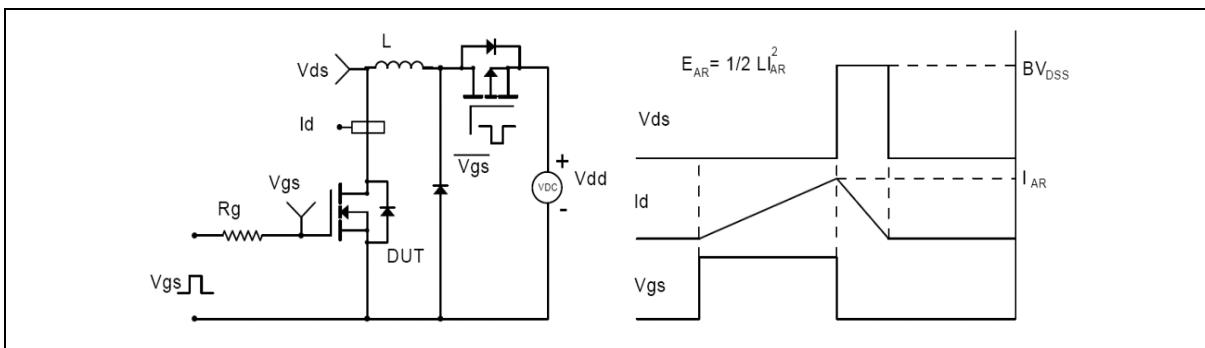
### Test circuits and waveforms



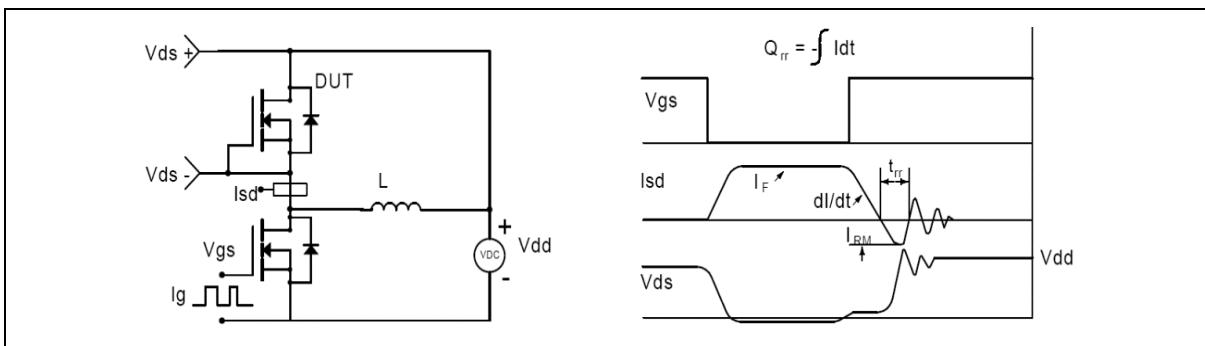
**Figure 1. Gate charge test circuit & waveform**



**Figure 2. Switching time test circuit & waveforms**

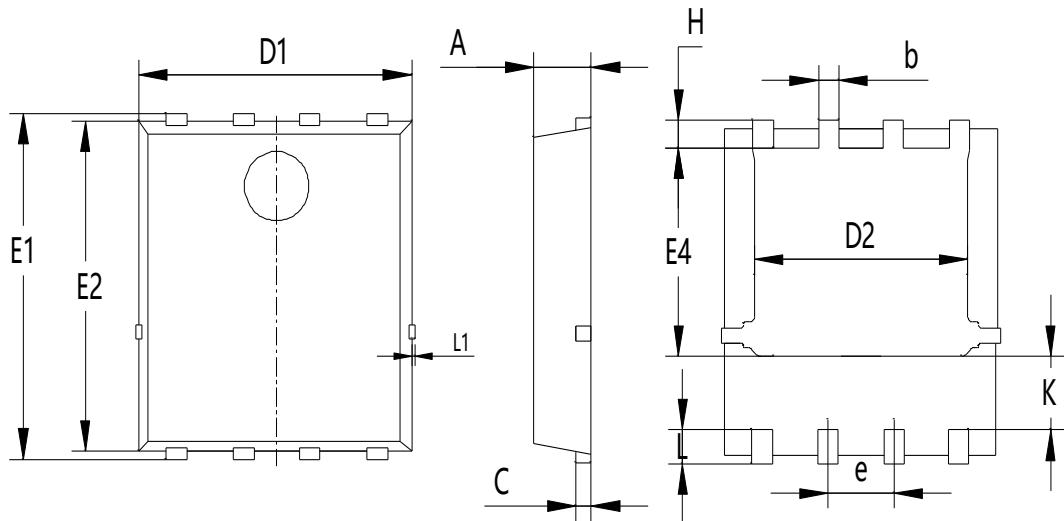


**Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms**



**Figure 4. Diode reverse recovery test circuit & waveforms**

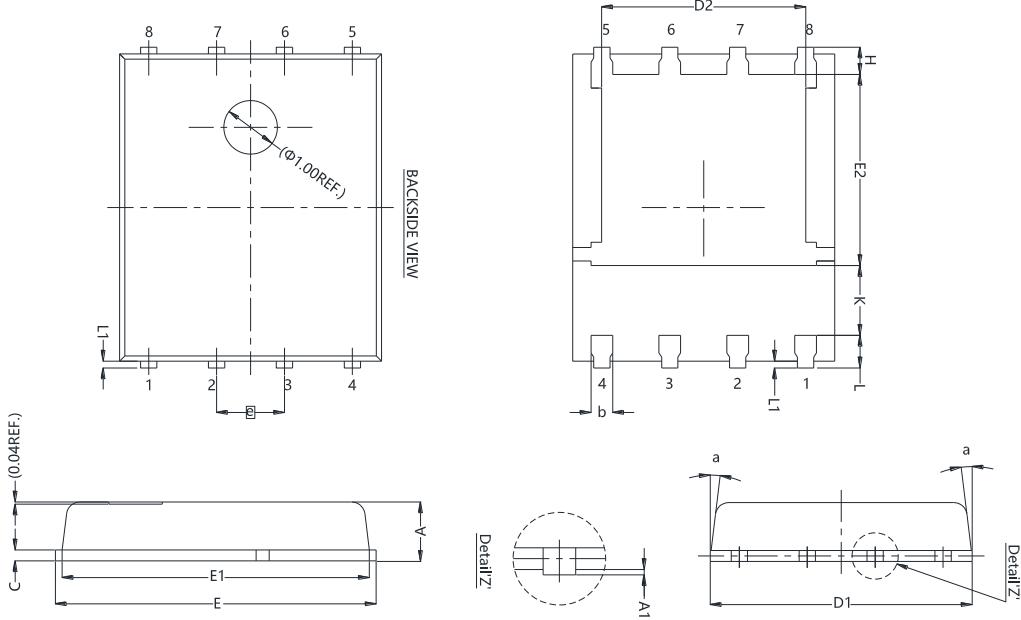
### Package Information



Symbol	mm		
	Min	Nom	Max
A	1.00	1.10	1.20
b	0.30	0.40	0.50
c	0.154	0.254	0.354
D1	5.00	5.20	5.40
D2	3.80	4.10	4.25
e	1.17	1.27	1.37
E1	5.95	6.15	6.35
E2	5.66	5.86	6.06
E4	3.52	3.72	3.92
H	0.40	0.50	0.60
L	0.30	0.60	0.70
L1	0.12 REF		
K	1.15	1.30	1.45

Version 1: PDFN5\*6-P package outline dimension

## Package Information



Symbol	mm		
	Min	Nom	Max
A	0.90	1.00	1.10
A1	0.00	-	0.05
b	0.33	0.41	0.51
C	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.38	3.58	3.78
e	1.27 BSC		
H	0.41	0.51	0.61
K	1.10	-	-
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
a	0°	-	12°

Version 2: PDFN5\*6-M package outline dimension

## Ordering Information

Package Type	Units/Reel	Reels / Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
PDFN5*6-P	5000	2	10000	5	50000
PDFN5*6-M	5000	2	10000	5	50000

## Product Information

Product	Package	Pb Free	RoHS	Halogen Free
SFS04R02GF	PDFN5*6	yes	yes	yes

## Legal Disclaimer

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